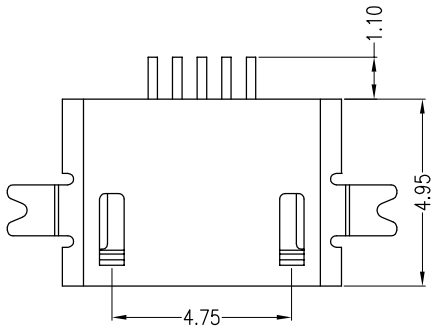
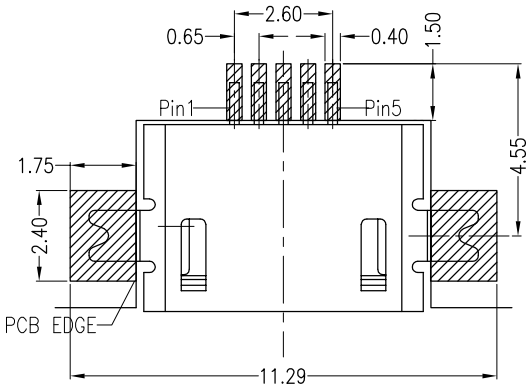
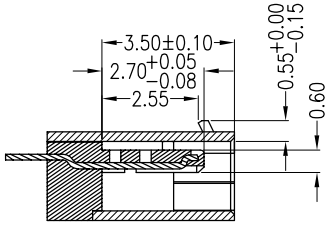
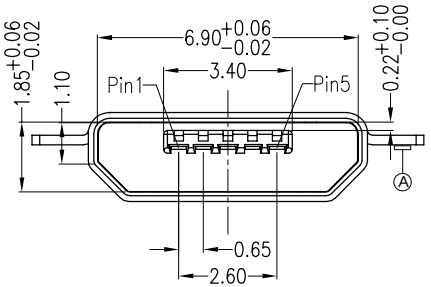
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE



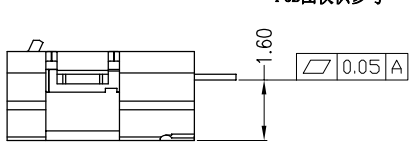


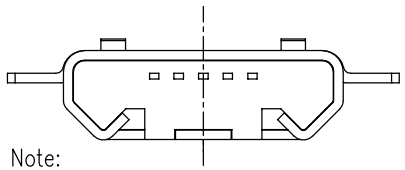




RECOMMANDED PCB LAYOUT

PCB图仅供参考





Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.15mm

1.3 Shell: copper alloy,t=0.25mm

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

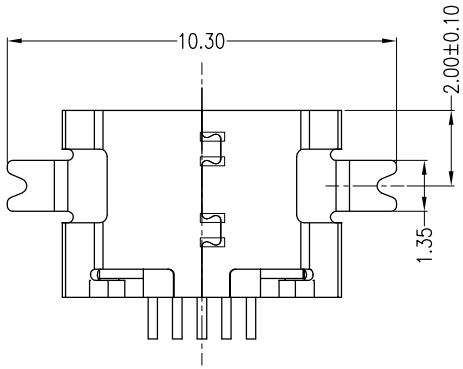
2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: -30°C~80°C



外壳材质

1:C2680R-H

外壳电镀

1:N50u''

2:雾T50u''

3:N+Au1u''(脚)

4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''

05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''

主体颜色 B:黑色

主体材质 1:LCP

端子材质 4:C5191R-EH

PART NO: USB-F06505-CB065		MATERAL: SEE NOTE	WFDCONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD
MODEL NO: XX		FINSH: SEE NOTE	TITLE: **Micro usb** 5s B Type SMT**脚破板1.6两只脚无翻边**
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED .x 0.15 .xx 0.10 .xxx 0.05 Ang. 1°		DR: LIU MIAO	DWG NO: A329 REV: A
		CHK: SIMON	SCALE: 5:1 DATE: 2012.05.04
		APP: DAVID	